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(71) Applicant: **LG INNOTEK CO., LTD.**, Seoul (KR)

(72) Inventors: **Myung Jae KWON**, Seoul (KR); **Sang Hyuck NAM**, Seoul (KR); **Jin Hyoung PARK**, Seoul (KR)

(73) Assignee: **LG INNOTEK CO., LTD.**, Seoul (KR)

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(57) **ABSTRACT**

A semiconductor package according to an embodiment includes a first insulating layer including a through hole; an insulating member disposed in the through hole of the first insulating layer; a first electrode layer disposed on the insulating member; a second insulating layer disposed on the first electrode layer; and a first through electrode passing through the second insulating layer, wherein the first through electrode overlaps the first electrode layer and the insulating member in a vertical direction.

